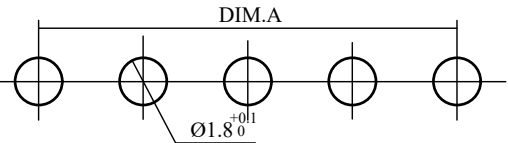
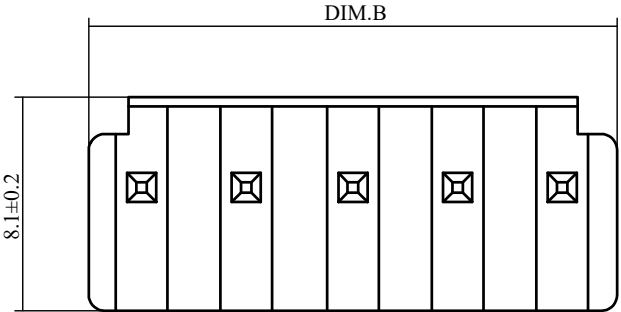
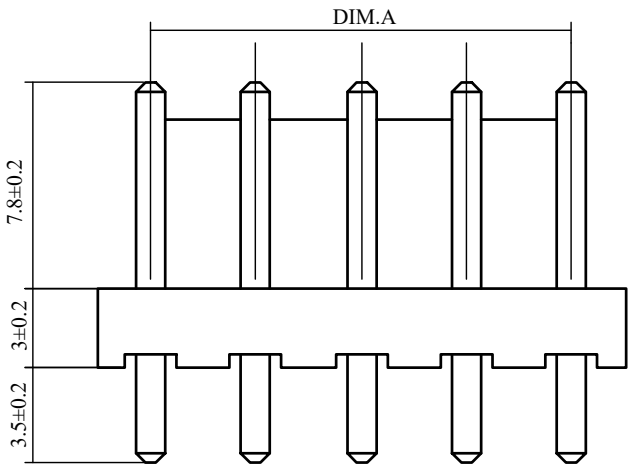
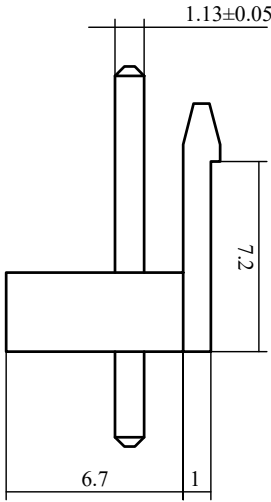


REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
1.00		初版发行	2018-05-28	瞿寿坤	胡海萍	胡海萍

NUMBER OF PINS	DIM.A	DIM.B
10P	35.64	39.60
9P	31.68	35.64
8P	27.72	31.68
7P	23.76	27.72
6P	19.8	23.76
5P	15.84	19.8
4P	11.88	15.84
3P	7.92	11.88
2P	3.96	7.92



PCB LAYOUT

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X.		X°.	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	

技术要求:

- 1) 材质: 见附表;
- 2) 电镀: 见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

适应基板厚度: 1.2mm~1.6mm

温度范围: -25°C~85°C

额定电压: 250V AC/DC

额定电流: 7A

接触电阻: ≤0.01Ω

绝缘电阻: ≥1000MΩ

耐压: 1500V AC/minute

2	PIN	n PCS	材质: 黄铜, 电镀: 镀亮锡60u"MIN		
1	Housing	1 PCS	材质: PA66, 颜色: 本色		
NO.	NAME	Q'TY	DESCRIPTION		
<b>深圳市虹成电子有限公司</b>					
DRAW :	瞿寿坤	2018-04-22	TITLE:	DRAW NAME:	
DESIGN:	瞿寿坤	2018-04-22	WAFER 3.96VHA 立式 DIP		HCZZ0324-4
CHECK:	胡海萍	2018-04-22	SERIES: 1501 SERIES		DRAW NO.:
APPROVED	胡海萍	2018-04-22	P/N:		UNIT: mm
CUSTOMER DRAWING			REV. 1.00	SCALE N/A	SHEET: 1/1